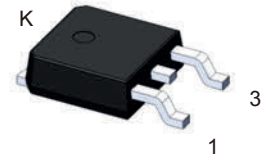


Features

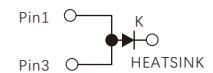
- Power pack
- Metal silicon junction, majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High forward surge capability
- High frequency operation
- High temperature soldering guaranteed: 260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU



TO-252

Mechanical Data

- Case: JEDEC TO-252
- Molding compound meets UL94V-0 flammability rating
- Terminals: Lead solderable per J-STD-002 and JESD22-B102
- Polarity: As marked



Schematic Diagram

Applications

For use in low voltage, high frequency inverters, DC/DC converters, free wheeling, and polarity protection applications

Maximum Ratings

(Ratings at 25°C ambient temperature unless otherwise specified)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	40	V
Maximum Forward Average Rectified Current (See Figure.1)	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	150	A
Typical Thermal Resistance, from Junction to Case	$R_{\theta JC}$	2.5	°C/W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +150	°C

Electrical Characteristics

(Pin 1&3 is shorted, $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Typ.	Max.	Unit	
Instantaneous Forward Voltage ¹	V_F	$I_F=5A$	$T_J=25^\circ\text{C}$	0.50	0.55	V
			$T_J=125^\circ\text{C}$	0.42	-	
Reverse Current ²	I_R	$V_R=40V$	$T_J=25^\circ\text{C}$	-	100	μA
			$T_J=125^\circ\text{C}$	-	40	mA
Typical Junction Capacitance	C_J	4V, 1MHz	230	-	pF	

Notes:

1. Pulse test: 300μs pulse width, 1% duty cycle
2. Pulse test: pulse width ≤40ms

Ratings and Characteristics Curves

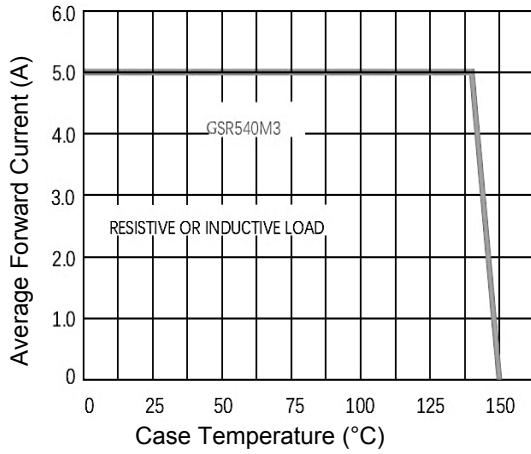


Figure 1. Forward Current Derating Curve

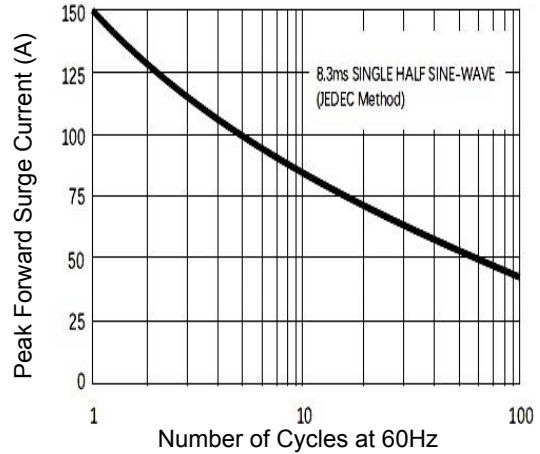


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

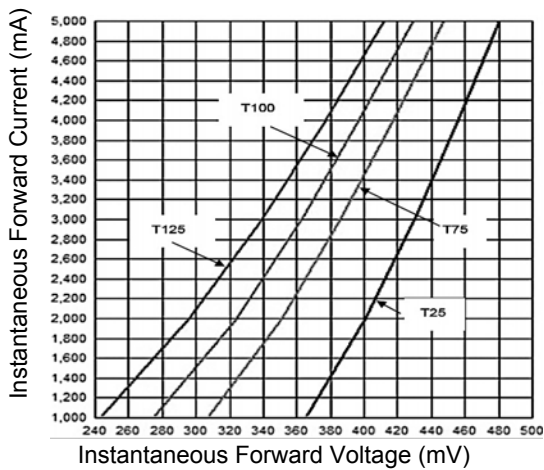


Figure 3. Typical Instantaneous Forward Characteristics

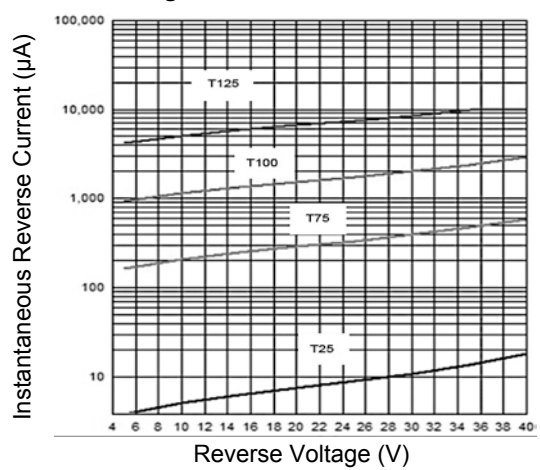


Figure 4. Typical Reverse Characteristics

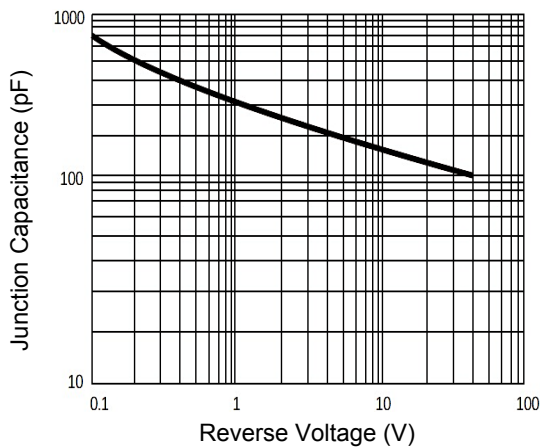
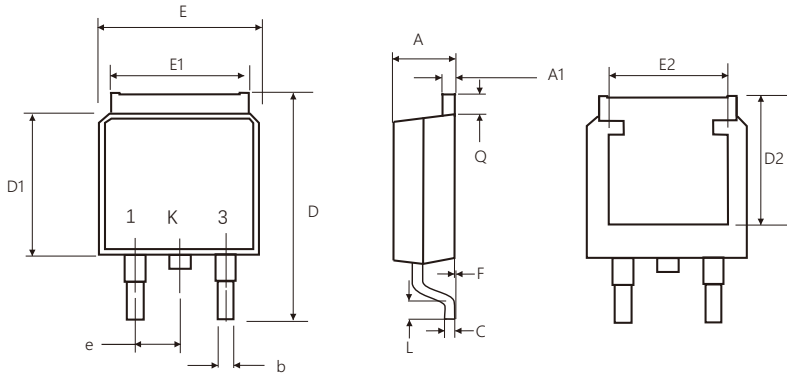


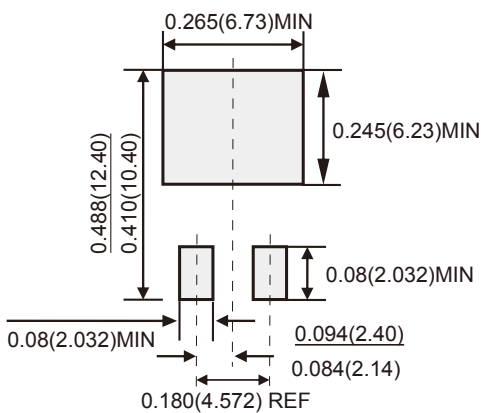
Figure 5. Typical Junction Capacitance

Package Outline Dimensions (TO-252)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.15	2.65	0.085	0.104
A1	0.42	0.58	0.017	0.023
e	2.14	2.40	0.084	0.094
b	0.64	0.89	0.025	0.035
Q	0.88	1.27	0.035	0.050
C	0.42	0.58	0.017	0.023
D	9.00	10.41	0.354	0.410
D1	5.60	6.22	0.220	0.245
E	6.20	6.73	0.244	0.265
E1	5.21	5.46	0.205	0.215
L	1.00	-	0.039	-
F	0.01	0.11	0.000	0.004
D2	5.11	5.58	0.201	0.220
E2	4.31	5.33	0.170	0.210

Recommended Pad Layout



Note:

1. Unit in inches (millimeters)
2. Pad layout for reference

Order Information

Device	Package	Marking	Carrier	Quantity
GSR540M3	TO-252	SR540M3	Tape & Reel	2,500 Pcs / Reel

For more information, please contact us at: inquiry@goodarksemi.com